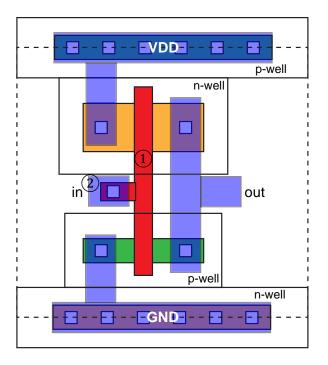


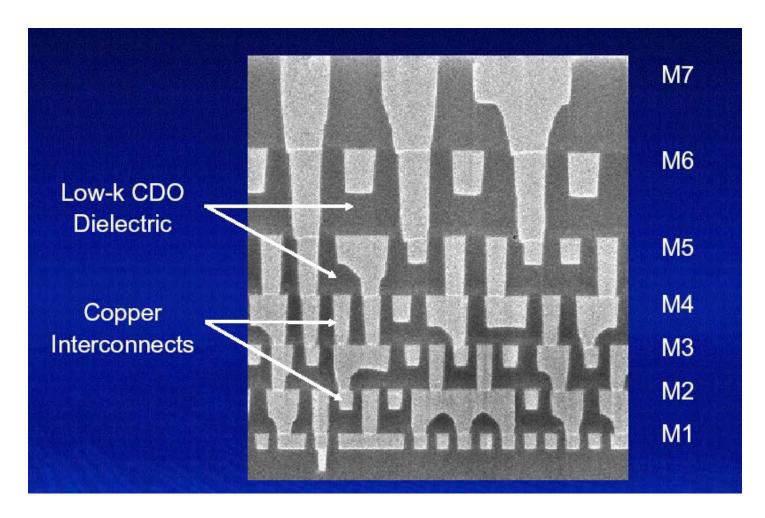


- Input
 - Layout (GDSII stream format)
 - A set of geometric objects

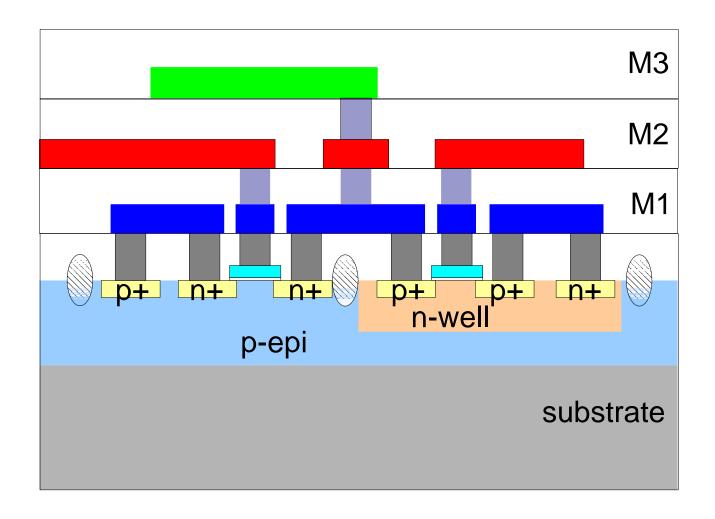


- ①: Layer id 3, polygon { 50, 40, 70, 40, 70, 220, 50, 220, 50, 140, 20, 140, 20, 110, 50, 110, 50, 40 }
- 2): Layer id 7, rectangle { 10, 105, 40, 150 }

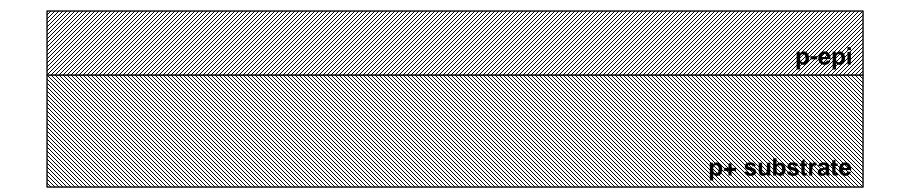




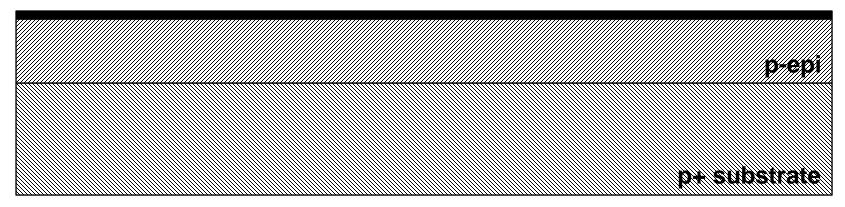








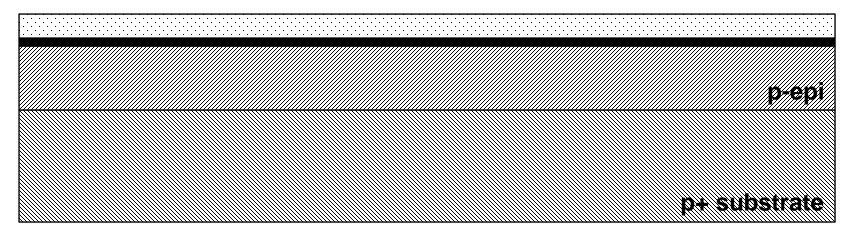




SiO₂

Gate-oxide deposition

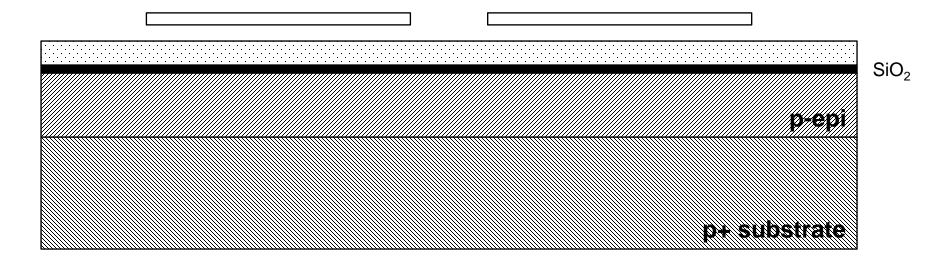




SiO₂

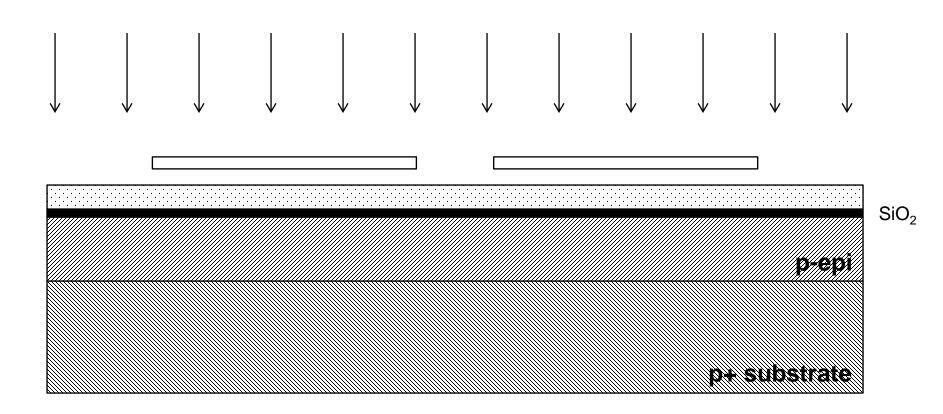
Photoresist





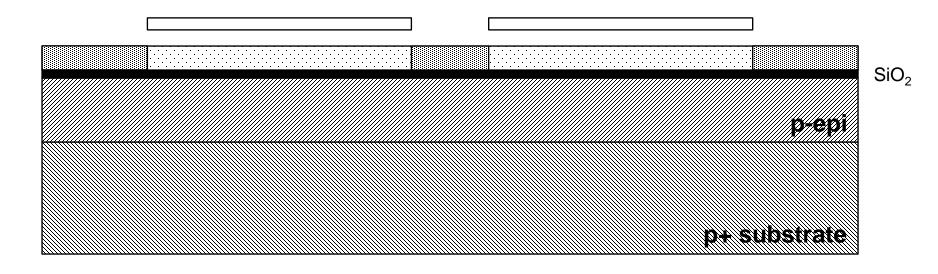
Mask





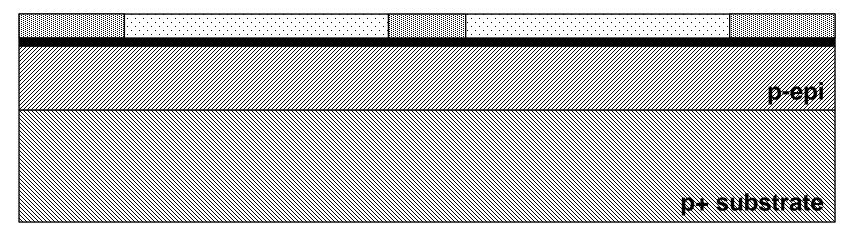
Expose (photolithography)





After photolithography

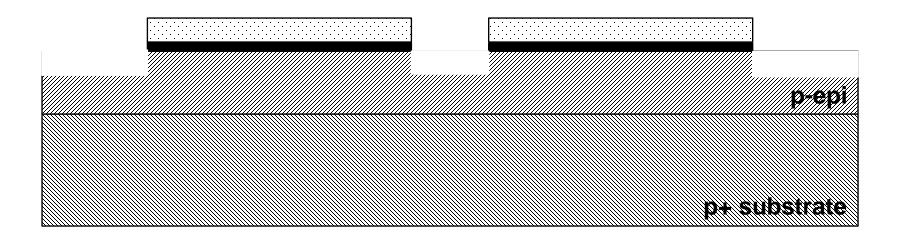




 ${\rm SiO_2}$

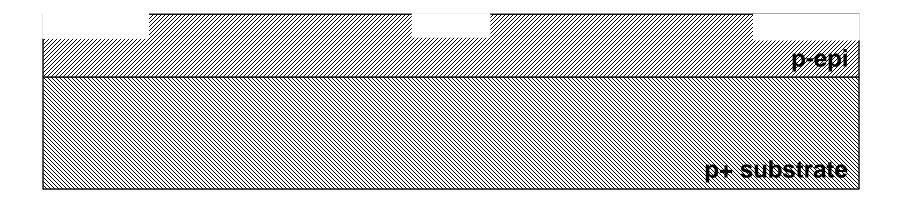
Remove mask





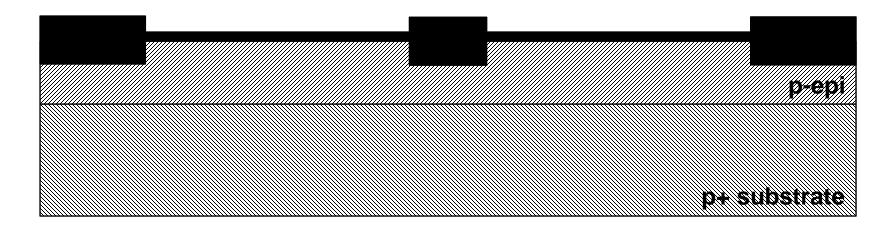
Etching





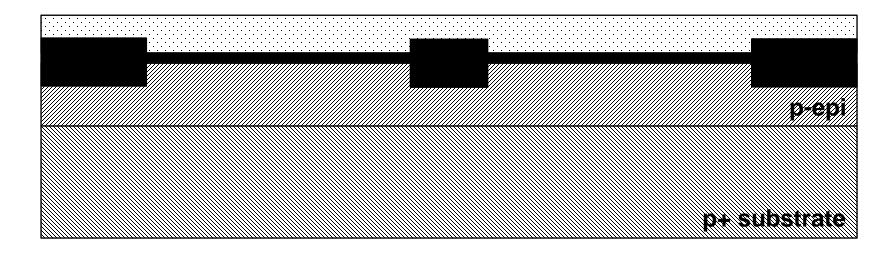
Etching





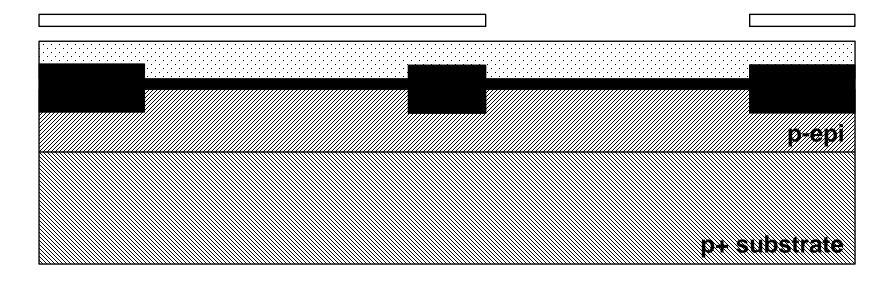
Oxide deposition





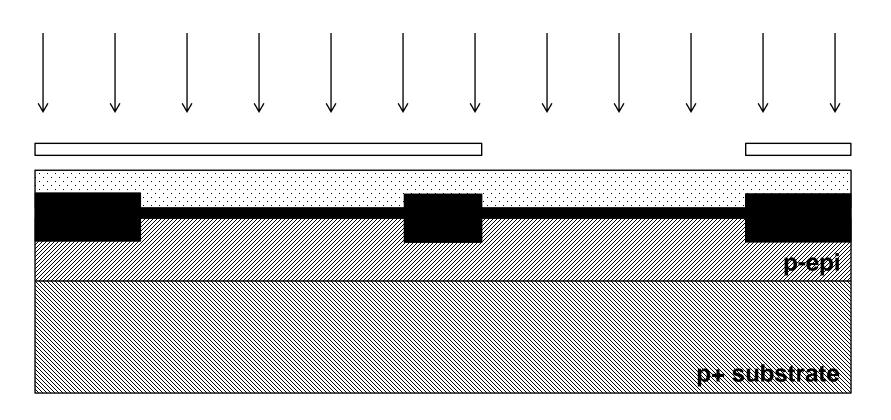
Photoresist





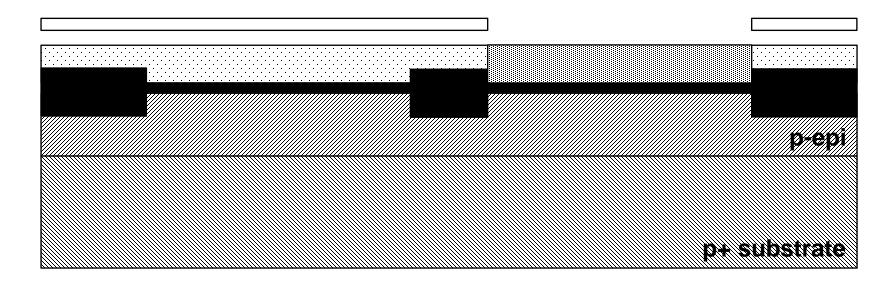






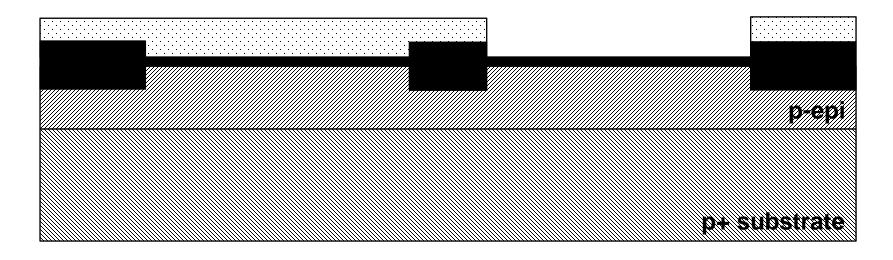
Photolithography





After photolithography

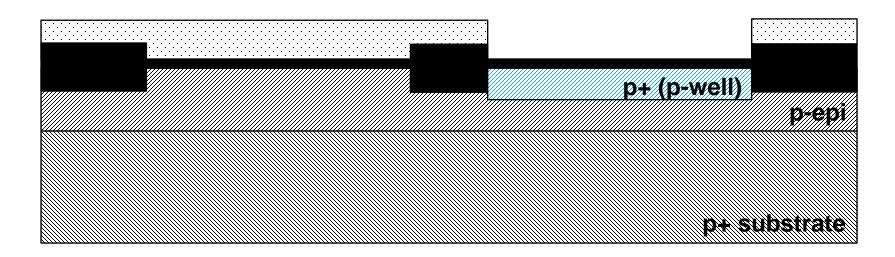




Etch



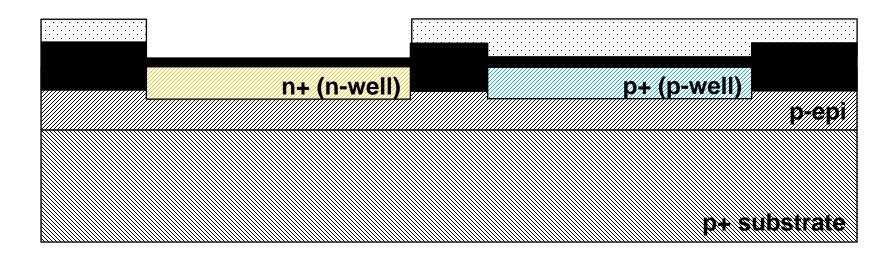




Doping

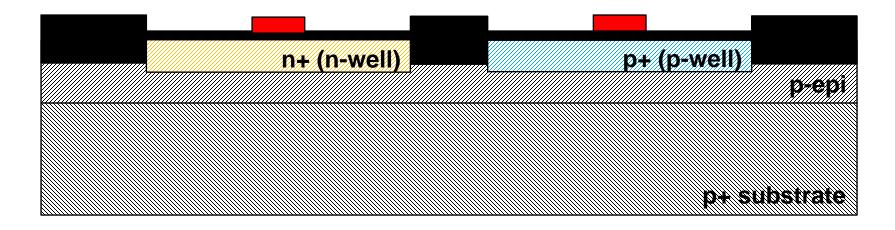






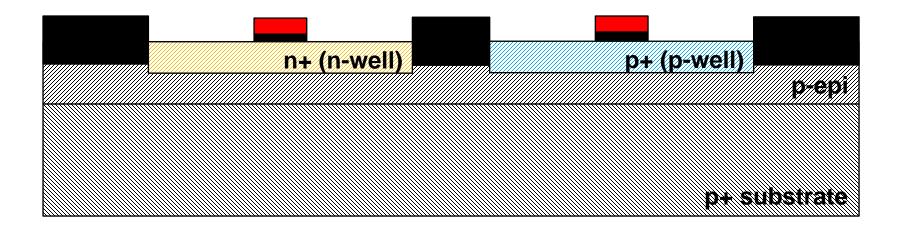
Doping





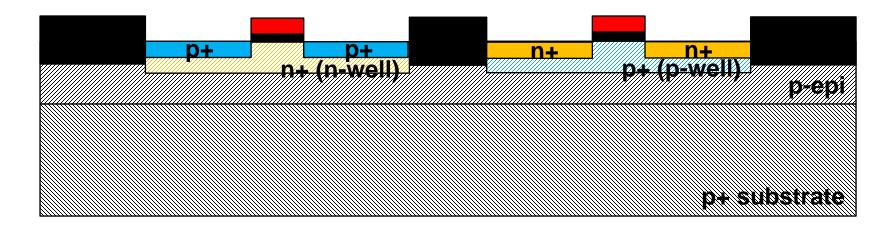
Poly





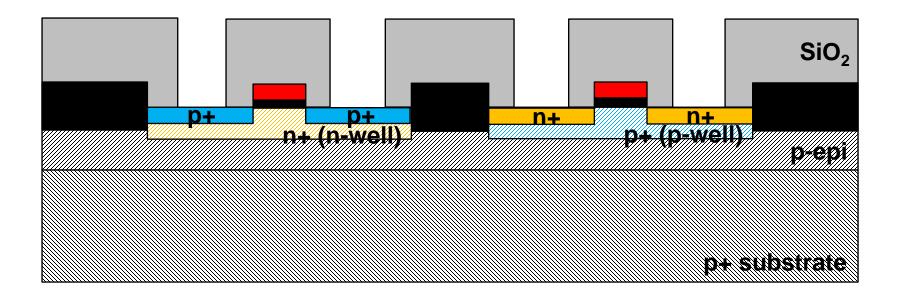
Etch





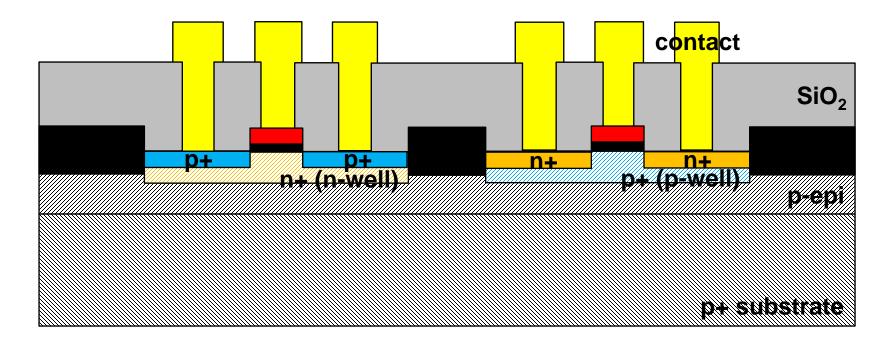
Doping





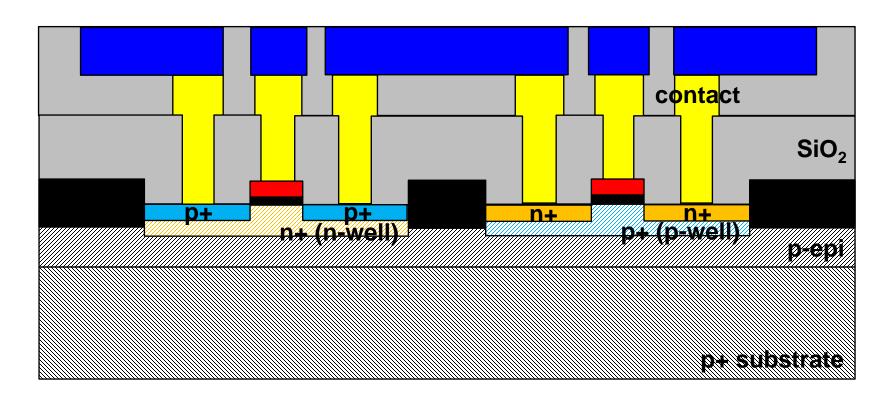
Oxide deposition





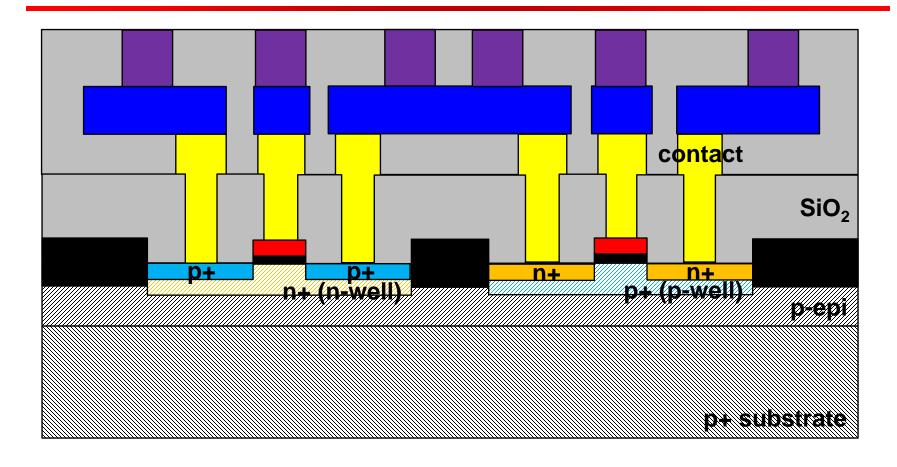
Contact





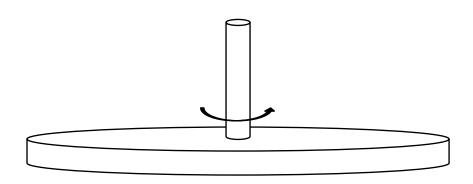
Metal 1

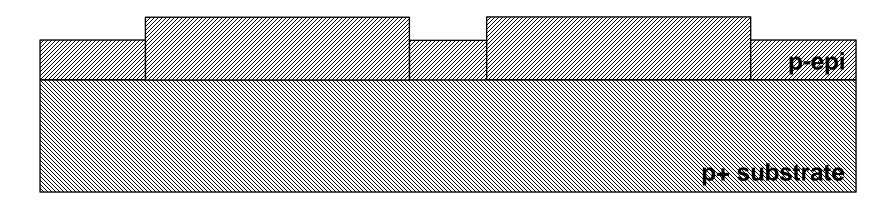




Via12







Chemical-mechanical-polishing (CMP)



